

IN THE CLAIMS

Please cancel claims 15 and 16 and amend the claims as follows.

- Sub C1
14. (Amended) An apparatus comprising:
a first substrate with a semiconductor film formed thereon;
wherein said semiconductor film demarcated from a rest of said first substrate
by a damaged surface with the damaged surface being removed; and
a second substrate with a metal film formed thereon, said second substrate
bonded with the metal film to said semiconductor film of said first substrate.

- Sub C4
20. (Amended) An apparatus comprising:
a substrate;
a first oxide film formed on said substrate;
a metal film formed on said first oxide film;
the first oxide film debonds the metal film from the substrate;
a second oxide layer formed on said metal film; and
a semiconductor film formed on said second oxide film, said semiconductor
film having a least one active device formed therein.

21. (Amended) The apparatus of claim 20 wherein said metal film includes a
noble metal.